



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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CSM Series

Board Mount Heat Sink For TO-220 Devices



The economically priced CSM Series is suitable for use with TO-220 devices found in active components as well as power resistors. With surface areas ranging from 1188 Sq. mm to 6645 Sq. mm, the CSM family comes in 5 configurations, all of them with Black Anodized surface treatment. These heatsinks

offer a range of thermal performance from 18.0 to 9.8 C/W. Each device offers solder able mounting feet and anywhere from 1, 2 or 3 mounting holes are available for convenient device attachment.

SERIES SPECIFICATIONS

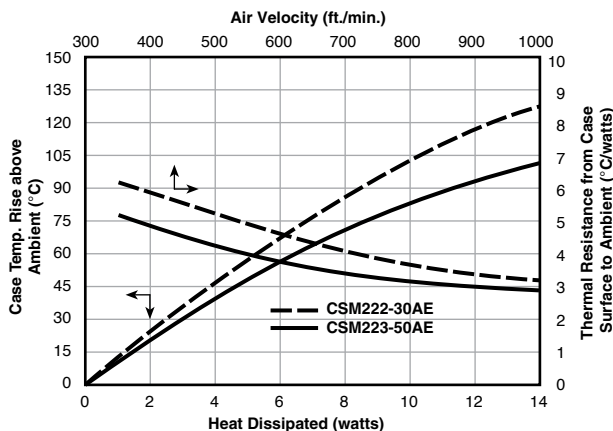
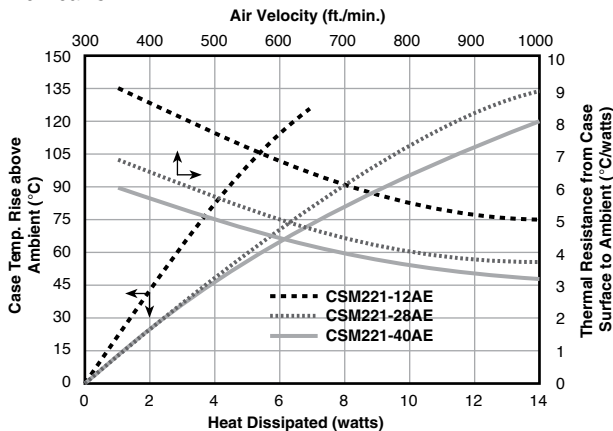
Heatsink Part Number	Surface Area (in ² / mm ²)	Weight (oz / g)	Length L (mm)	Thermal Res.* (°C/W)
CSM221-12AE	1.84 / 1,188	0.13 / 3.7	12	18.0
CSM221-28AE	4.30 / 2,772	0.3 / 8.5	28	12.8
CSM221-40AE	6.14 / 3,960	0.43 / 12.2	40	12.1
CSM222-30AE	6.25 / 4,029	0.5 / 14.2	30	11.3
CSM223-50AE	10.30 / 6,645	0.6 / 17.0	50	9.8

*Free convection at 10 watts dissipation

CHARACTERISTICS

Heat Dissipation

Heat dissipation is the total for ALL DEVICES attached to the heat sink



Heat Sink Aluminum Alloy 6063-T5 or Equivalent with either degreased or black anodized finish.

Solder Foot Cold-rolled Steel, surface tin plated.

Interface Thermal Resistance for improvement, use thermal joint compound, 0.005 Grafoil (TGon 800 by Laird), or phase change material (Hi-Flow by Bergquist)

Insulator (Optional) Sil-Pad 900-S, K6 800-S and K10 by Bergquist

(continued)

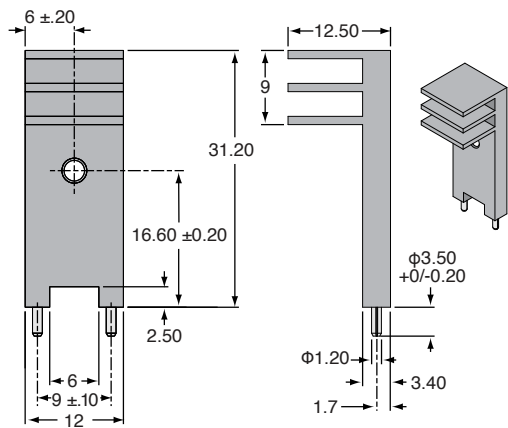
CSM Series

Board Mount Heat Sink For TO-220 Devices

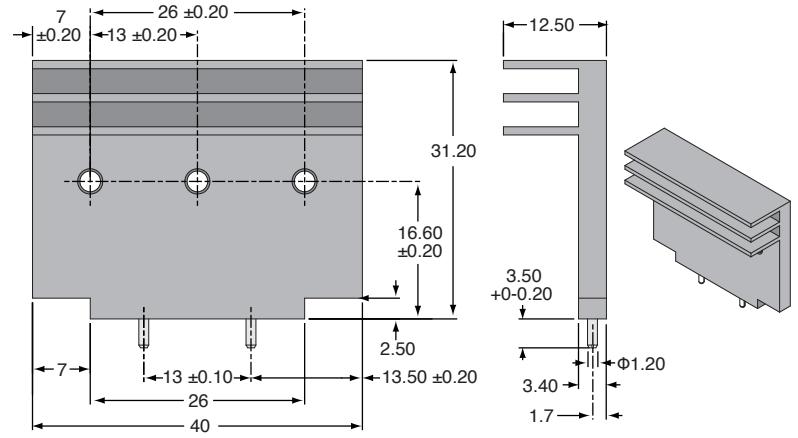
DIMENSIONS

Dimensions in mm; M3*0.5P thread Tapping. JIS-2b standard chamfer 0.3m

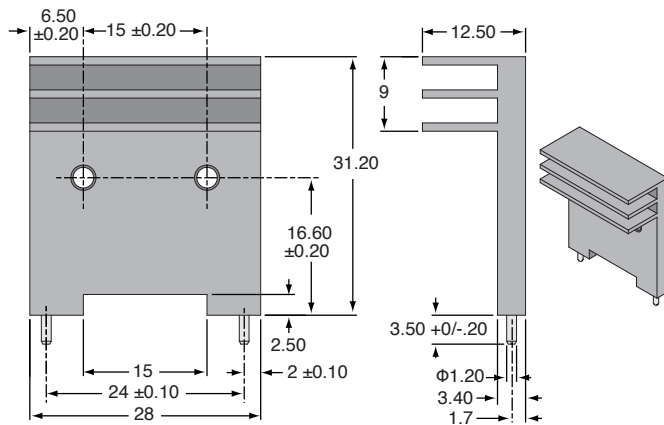
CSM221-12AE



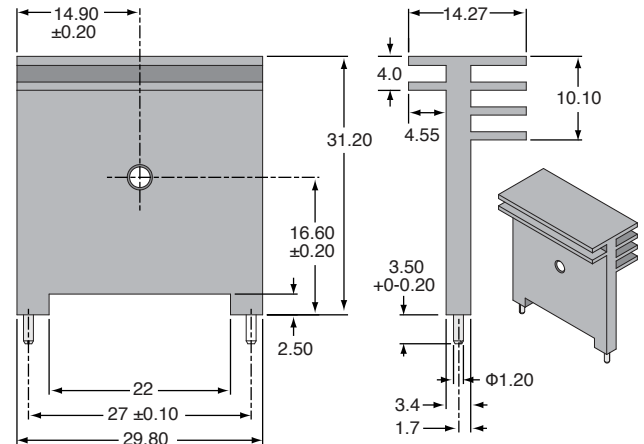
CSM221-40AE



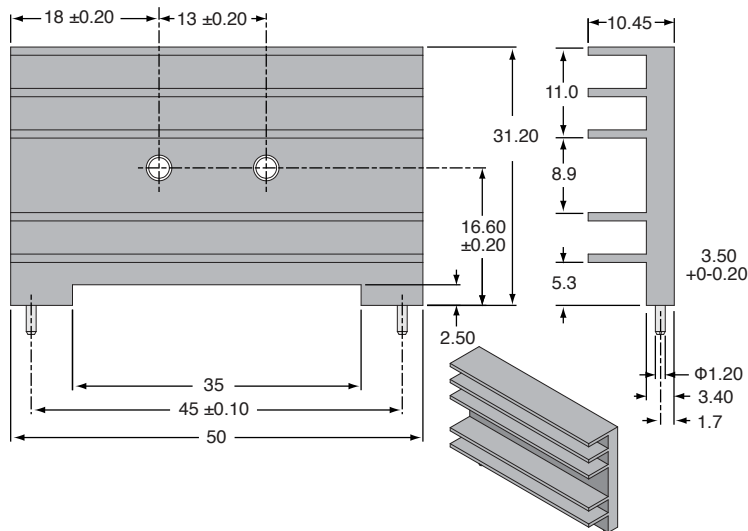
CSM221-28AE



CSM222-30AE



CSM223-50AE



HOW TO ORDER

RoHS Compliant
CSM221-12AE
 Series Extrusion type Extrusion width Black anodized